			INI OKMA	TION DISCLOSURE STATEMEN				
ORM PTO 1449 (madified) U.S. DEPARTMENT OF COMMERCE				2006_0772A		SERIAL NO. 10/581,256		
	FREFERE	D TRADEMARK OFFIC		APPLICANT Mitsuhiro OKUNE et al.				
(Use several sheets if necessary) Date Submitted to PTO: July 22, 2008				FILING DATE May 31, 2006		GROUP 1765		
	io odbiiii	33 to 1 13 to 3 to 1		S. PATENT DOCUMENTS		1703		
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	SS FILING DATE IF APPROPRIATE	
	AA	5,871,659	2/1999	Sakano et al.				
	AB	4,214,946	7/1980	Forget et al.				
	AC							
	AD							
	AC							
	AF							
			FOR	EIGN PATENT DOCUMENTS				
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	S SUBCLASS TRANSLATION YES NO		
	BA							
	BA							
	AC							
	ÂD							
	AC							
	_	ОТНЕ	R DOCUMENT(S)	(Including Author, Title, Date, Pertin	ent Pages, Etc.)			
	CA	Supplementary Eurounterpart to the p		Report issued <u>June 11, 2</u> tion	008 in EP 04 8	9793, which is	a foreign	
	СВ	Meint J. DE BOER et al., "Guidelines for Etching Silicon MEMS Structures Using Fluorine High-Density Plasma at Cryogenic Temperatures", JOURNAL OF MICROELECTROMECHANICAL SYSTEMS IEEE Service Center, Piscattaway, NJ, vol. 11, no. 4, August 1, 2002 (8/1/2002)						
	СС	Performance Etching	for Ultra large-Sc	scharge Frequency in Plasma cale Integrated Circuits", JAPA I, no. 4A, Part 01, April 1, 2000	NESE JOURNAL	rge-Frequency Pla OF APPLIED PHYS	sma Source f SICS, Japan,	or Hig Societ
	CD							